



SOT23

plastic, surface-mounted package; 3 terminals; 1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body

9 January 2017

Package information

1. Package summary

Dimensions (mm)	2.9 x 1.3 x 1
Terminal position code	D (double)
Package type descriptive code	TO-236AB
Package outline version code	SOT23
Manufacturer package code	SOT23
Package type industry code	TO-236AB
Package outline version description	plastic, surface-mounted package; 3 terminals; 1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body
Package style descriptive code	SOT (small outline transistor)
Package body material type	P
JEDEC package outline code	TO-236AB
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	SC18_1999_CHAPTER_5_2
Mounting method type	S (surface mount)
Generic mounting and soldering information	AN10365_3
Reflow soldering footprint	SOT023_fr
Wave soldering footprint	SOT023_fw
Package life cycle status	REL
Major version date	18-9-2008
Minor version date	6-7-2012
Security status	COMPANY PUBLIC
Modified date	28-11-2012
Issue date	16-3-2006
Web publication date	28-11-2012
Initial web publication date	11-3-2011
Customer specific indicator	N
Maturity	Product
Package author	Nair Deepa
Package approver	Nair Deepa

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A	seated height	0.9	-	1	1.1	mm
D	package length	2.8	-	2.9	3	mm



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Symbol	Parameter		Min	Typ	Nom	Max	Unit
E	package width		1.2	-	1.3	1.4	mm
e	nominal pitch		-	-	1.9	-	mm
n ₂	actual quantity of termination		-	-	3	-	

2. Package outline

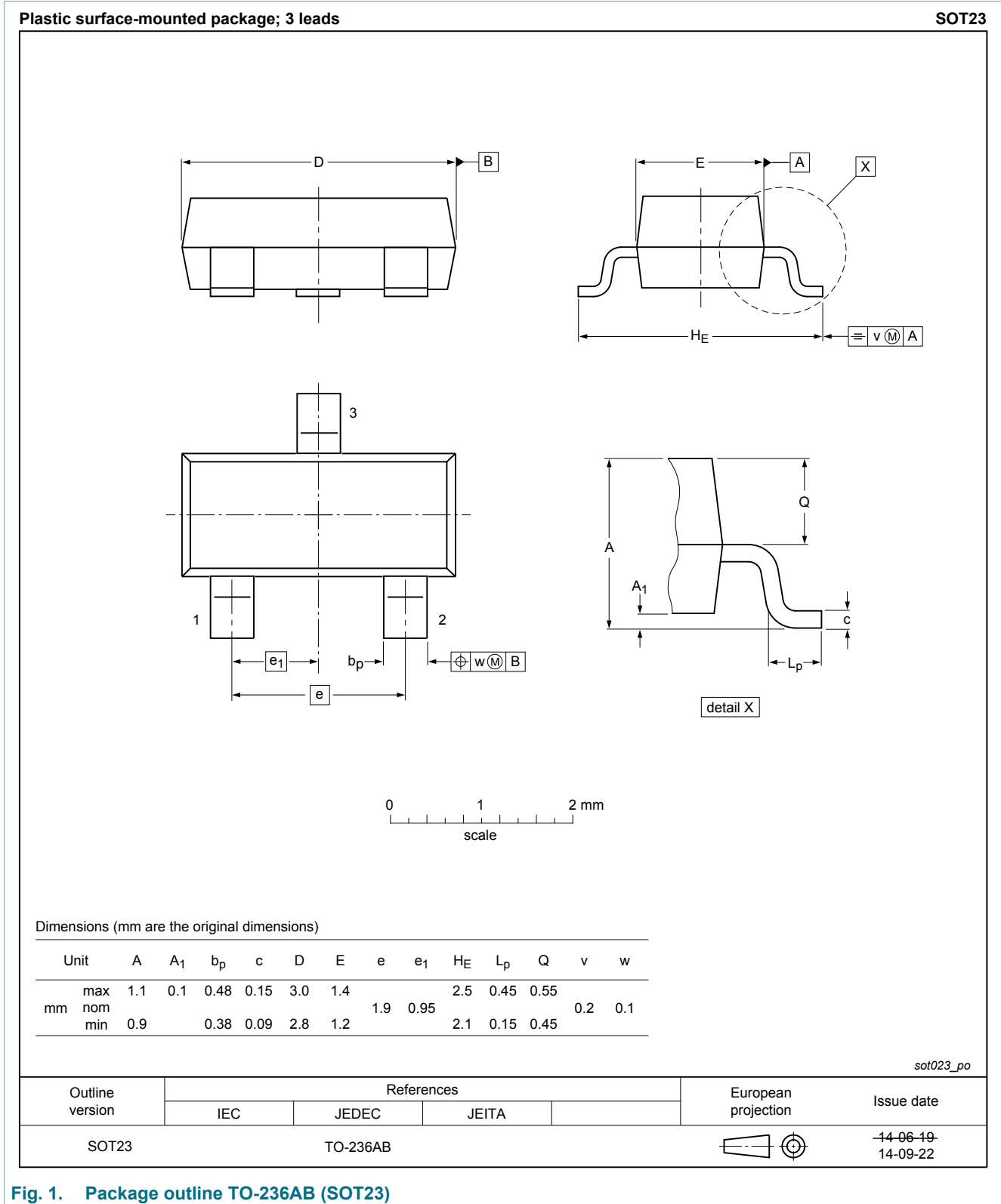


Fig. 1. Package outline TO-236AB (SOT23)

3. Soldering

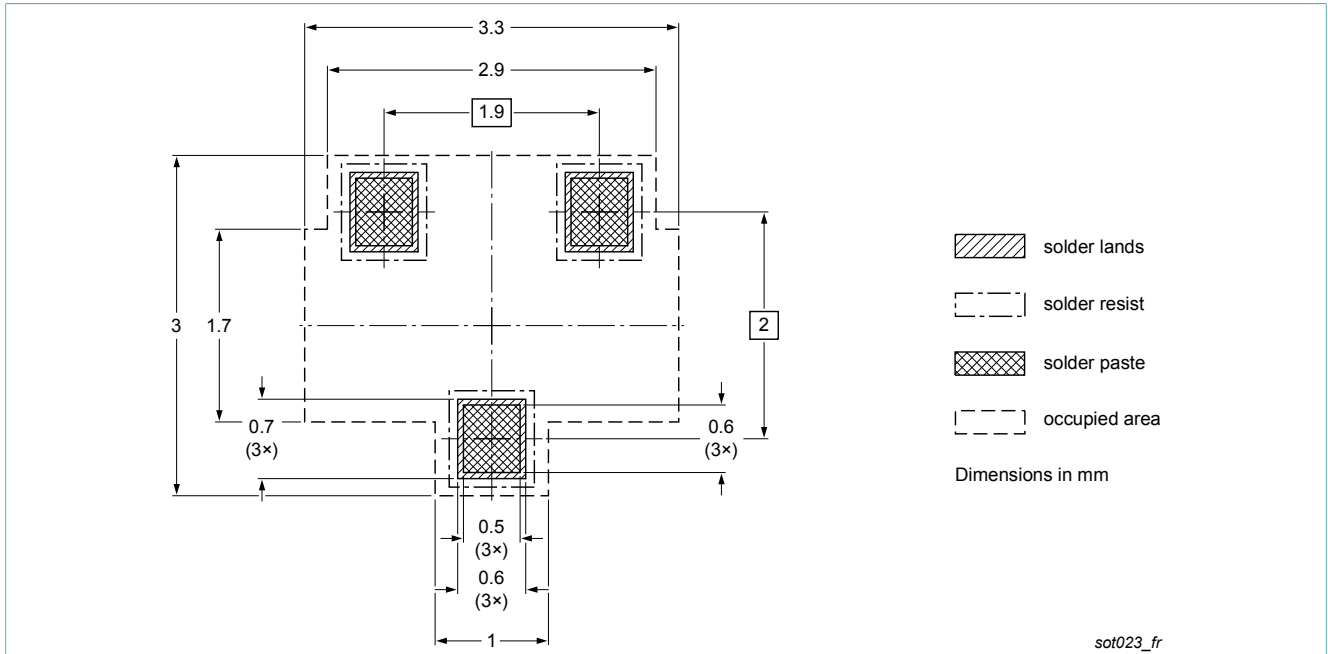


Fig. 2. Reflow soldering footprint for TO-236AB (SOT23)

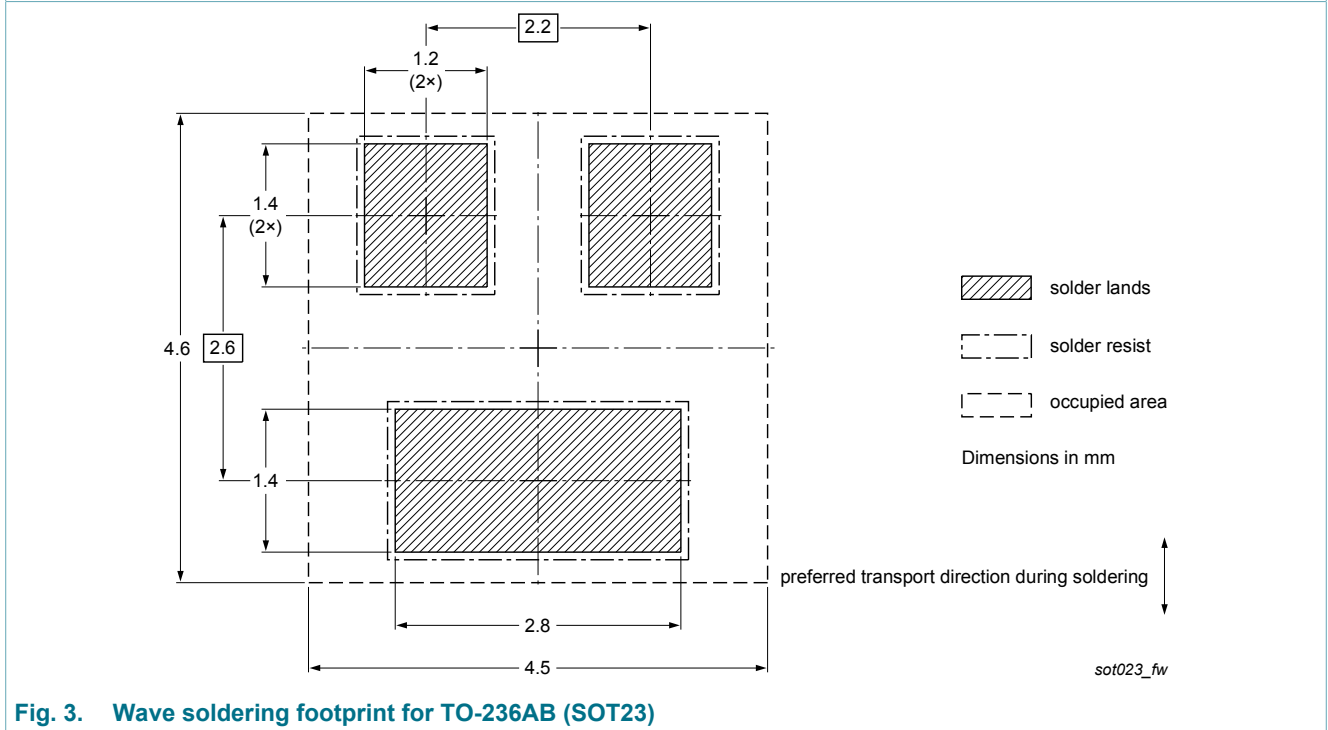


Fig. 3. Wave soldering footprint for TO-236AB (SOT23)

4. Legal information

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